

Silicon Carbide Power MOSFET Switching Optimized 1200V $36m\Omega$ Automotive N-Channel Enhancement Mode

Features

- Industry compatible drive voltage 15V...18V/-5V...0V
- Soft body diode with low Vds overshoot and ringing
- Low Rds(on) at high operating temperatures
- Improved device capacitances ratio (Ciss/Crss)
- High transient voltage robustness with improved lifetime
- · Halogen free, RoHS compliant
- Automotive Qualified (AEC-Q101) and PPAP Capable

Benefits

- Higher efficiency with lower switching losses and EMI
- Faster switching operation enabling high power density
- Enables system level price performance optimization
- · Reduction in system level cooling requirements

Typical Applications

- Motor Control
- EV On Board Battery Chargers (OBC)
- Automotive DC/DC Converters for EV/HEV

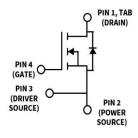


Package









Orderable Part number	Package type	Marking
E4MS036120K	TO-247-4	E4MS036120K

Key Parameters

Parameter	Symbol	Min.	Тур.	Max	Unit	Conditions	Note
Drain - Source Voltage	V _{DS}			1200			
Maximum Gate - Source Voltage	$V_{\rm GS(max)}$	-10		+23	V		
				55		$V_{GS} = 18 \text{ V}, T_{C} = 25 \text{ °C}, T_{J}$ $\leq 175 \text{ °C}$	
DC Continuous Drain Current	l _D			39	A	$V_{GS} = 18 \text{ V}, T_{C} = 100 \text{ °C}, T_{J}$ $\leq 175 \text{ °C}$	Note 1
Pulsed Drain Current	I _{DM}			193		t_{pmax} limited by T_{jmax} $V_{GS} = 18V, T_{C} = 25 ^{\circ}C$	
Power Dissipation	P _D			211	W	$T_{c} = 25^{\circ}C, T_{J} = 175^{\circ}C$	Note 2
Operating Junction and Storage Temperature	T _J , T _{stg}	-55		+175			
Solder Temperature	T _L			260	°C		

Note (1): Current limit calculated by $I_{D(max)} = \sqrt{(P_D/R_{DS(typ)}(T_{J(max)},I_{D(max)}))}$

Note (2): $P_D = (T_J - T_C)/R_{th(JC,max)}$

Electrical Characteristics (T_c = 25°C unless otherwise specified)

Symbol	Parameter	Min.	Тур.	Max.	Unit	Test Conditions	Note
V _{(BR)DSS}	Drain-Source Breakdown Voltage	1200			V	$V_{GS} = 0 \text{ V, } I_D = 100 \mu\text{A}$	
V	Cata Thread and Valtage	2	2.6	3.9	V	$V_{DS} = V_{GS}$, $I_D = 7.6 \text{ mA}$	Fig. 11
$V_{GS(th)}$	Gate Threshold Voltage		2.0		V	$V_{DS} = V_{GS}$, $I_D = 7.6 \text{ mA}$, $T_J = 175 ^{\circ}\text{C}$	Fig. 11
I _{DSS}	Zero Gate Voltage Drain Current		1	50	μΑ	$V_{DS} = 1200 \text{ V}, V_{GS} = 0 \text{ V}$	
I _{GSS}	Gate-Source Leakage Current		10	250	nA	$V_{GS} = 18 \text{ V}, V_{DS} = 0 \text{ V}$	
$V_{GS(op)}$	Recommended Turn on Gate-Source Voltage		+15+18		V		Refer to PRD-
G2(0p)	Recommended Turn off Gate-Source Voltage	1	-50				09634
			36	47		$V_{GS} = 18 \text{ V}, I_D = 27.6 \text{ A}$	
$R_{DS(on)}$	Drain-Source On-State Resistance		66		mΩ	$V_{GS} = 18 \text{ V}, I_D = 27.6 \text{ A}, T_J = 175 ^{\circ}\text{C}$	Fig. 4, 5, 6
			42 20			$V_{GS} = 15 \text{ V}, I_D = 27.6 \text{ A}$ $V_{DS} = 20 \text{ V}, I_D = 27.6 \text{ A}, T_J = 25^{\circ}\text{C}$	
g_{fs}	Transconductance		19		S	$V_{DS} = 20 \text{ V}, I_D = 27.6 \text{ A}, T_J = 175^{\circ}\text{C}$	Fig. 7
R _{DS(on)Tempco}	On resistance temperature coefficient		1.88			$V_{GS} = 18 \text{ V}, I_D = 27.6 \text{ A}$	Note 3
C _{iss}	Input Capacitance		2164			763 10 1715 2710 11	
			<u> </u>		_	$V_{GS} = 0 \text{ V}, V_{DS} = 1000 \text{ V}$	F: 47.40
C _{oss}	Output Capacitance		72		pF	$V_{GS} = 0 \text{ V, } V_{DS} = 1000 \text{ V}$ $f = 100 \text{ kHz}$ $V_{AC} = 25 \text{ mV}$	Fig. 17, 18
C _{rss}	Reverse Transfer Capacitance		3.2				
C_{iss}/C_{rss}	Capacitance Ratio		630				Note 4
E _{oss}	C _{oss} Stored Energy		46		μЈ		Fig. 16
$C_{o(er)}$	Effective Output Capacitance (Energy Related)		106		pF	V _{GS} = 0V, V _{DS} = 0800V	
$C_{o(tr)}$	Effective Output Capacitance (Time Related)		173		рі		
	Turn-On Switching Energy (Body Diode FWD)						
E_{on}	Tj=25C		303				Fig. 26, 29, 31
	Tj=175C		393			$V_{DS} = 800 \text{ V}, V_{GS} = -4 \text{ V}/18 \text{ V}, I_{D} = 27.6 \text{ A},$	
	Turn-Off Switching Energy (Body Diode FWD)				·μJ	$R_{G(ext)} = 2\Omega, L_{\sigma} = 25 \text{nH}$	
E_{off}	Tj=25C		18				Fig. 26, 29, 32
	Tj=175C		26				
$t_{d(on)}$	Turn-On Delay Time		12			$V_{DD} = 800 \text{ V}, V_{GS} = -4 \text{ V}/18 \text{ V}$	
t _r	Rise Time		3			$I_{D} = 27.6 \text{ A}, R_{G(ext)} = 2 \Omega,$ Timing relative to V_{DS} Inductive load	Fig. 27, 28
$t_{d(off)}$	Turn-Off Delay Time		29		ns		
t _f	Fall Time		4				
$R_{G(int)}$	Internal Gate Resistance		2.4		Ω	f = 1 MHz	
Q_{gs}	Gate to Source Charge		24			$V_{DS} = 800 \text{ V}, V_{GS} = -4 \text{ V}/18 \text{ V}$	
Q_{gd}	Gate to Drain Charge		23		nC	$I_D = 27.6 \text{ A}, T_J = 25^{\circ}\text{C}$	Fig. 12
Qg	Total Gate Charge	1	88		1	Per IEC60747-8-4 pg 21	

Note (3): $R_{DS(on)Tempco}$ refers to $R_{DS(on)}$ at 175 C/ $R_{DS(on)}$ at 25C, E4MS 1200V product family value

Note (4): Capacitance ratio is a FOM for Partial turn-on immunity PRD-06933, E4MS 1200V product family value

Co(er), a lumped capacitance that gives the same stored energy as Coss while Vds is rising from 0 to 800V Co(tr), a lumped capacitance that gives the same charging time as Coss while Vds is rising from 0 to 800V

Reverse Diode Characteristics (T_c = 25°C unless otherwise specified)

Symbol	Parameter	Тур.	Мах.	Unit	Test Conditions	Note
V	Diada Famurand Valtage	5.2		V	$V_{GS} = -4 \text{ V}, I_{SD} = 13.8 \text{ A}, T_{J} = 25 \text{ °C}$	Fig. 8, 9,
V _{SD}	Diode Forward Voltage	4.6		٧	V _{GS} = -4 V, I _{SD} = 13.8 A, T _J = 175 °C	10
Is	Continuous Diode Forward Current		34	Α	$V_{GS} = -4 \text{ V, } T_{C} = 25^{\circ}\text{C}$	
I _{SM}	Diode Pulse Current		193	А	$V_{GS} = -4 \text{ V}$, pulse width t_p limited by T_{jmax} max	
t _{rr}	Reverse Recovery Time	11		ns		
Q _{rr}	Reverse Recovery Charge	335		nC	V_{GS} =-4 V, I_{S} =27.6 A, V_{SD} =800V	
I _{RRM}	Peak Reverse Recovery current	49		А	T _J =175°C, diF/dt= 7.6 A/ns	
	Reverse recovery Energy				V ₋ =800 V, ₋ =27.6 A.	
E _{RR}	Tj=25C	29		μЈ	$V_{DS} = 800 \text{ V, } I_{D} = 27.6 \text{ A,}$ $V_{CS} = -4V/18V, R_{C(CON)} = 2 \Omega, L\sigma = 25 \text{ nH}$	
	Tj= 175C	35			V_{GS} =-4V/18V, $R_{G(on)}$ =2 Ω , L_{σ} =25nH	

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Unit	Test Conditions	Note
$R_{\theta JC}$	Thermal Resistance from Junction to Case	0.55	0.71	°C/W		

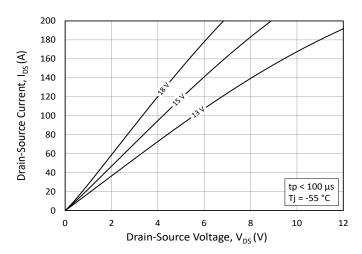


Figure 1. Output Characteristics T_J = -55°C

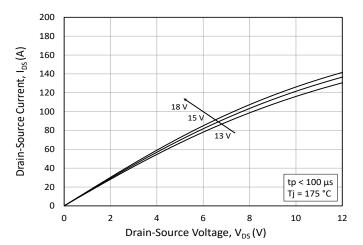


Figure 3. Output Characteristics T_J = 175°C

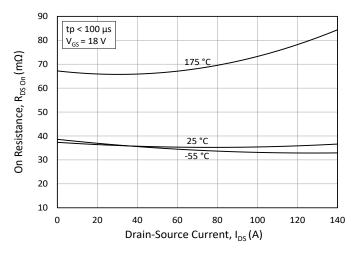


Figure 5. On-Resistance vs. Drain Current For Various Temperatures

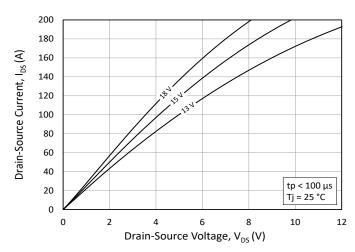


Figure 2. Output Characteristics T_J = 25°C

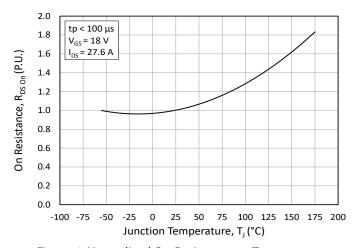


Figure 4. Normalized On-Resistance vs. Temperature

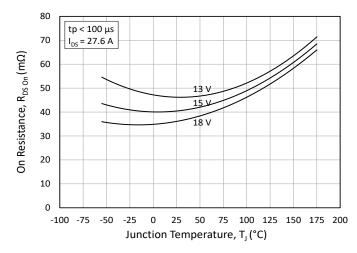


Figure 6. On-Resistance vs. Temperature For Various Gate Voltage

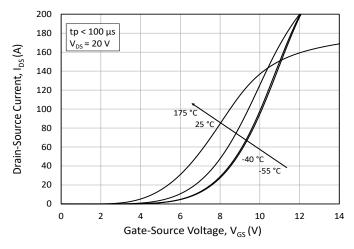


Figure 7. Transfer Characteristic for Various Junction Temperatures

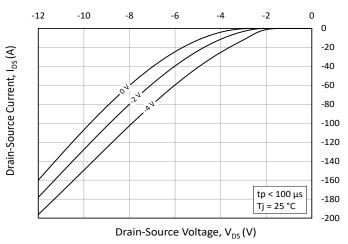


Figure 9. Body Diode Characteristic at 25°C

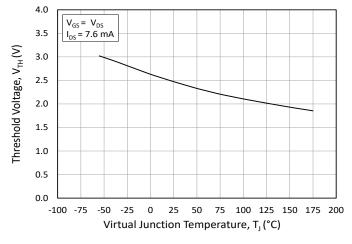


Figure 11. Threshold Voltage vs. Temperature

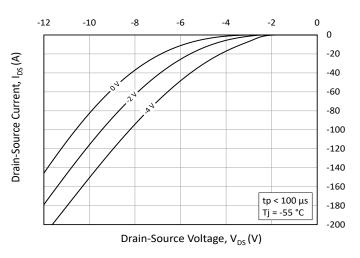


Figure 8. Body Diode Characteristic at -55°C

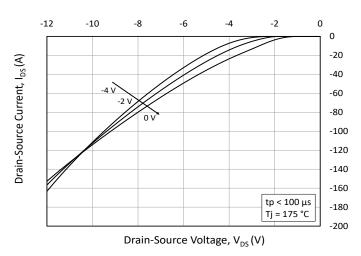


Figure 10. Body Diode Characteristic at 175°C

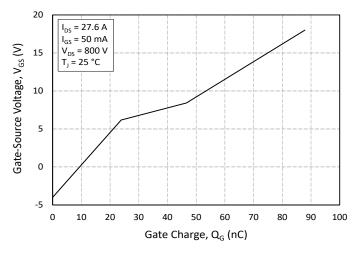


Figure 12. Gate Charge Characteristics

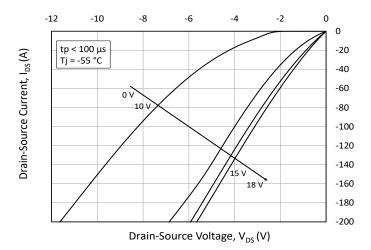


Figure 13. 3rd Quadrant Characteristic at -55°C

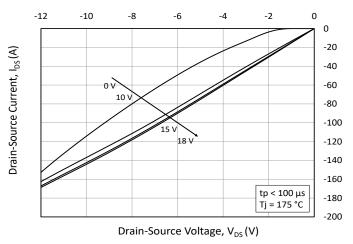


Figure 15. 3rd Quadrant Characteristic at 175°C

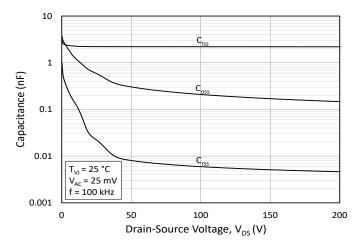


Figure 17. Capacitances vs. Drain-Source Voltage (0 - 200 V)

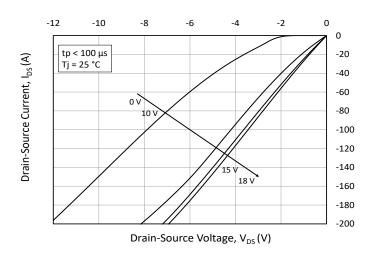


Figure 14. 3rd Quadrant Characteristic at 25°C

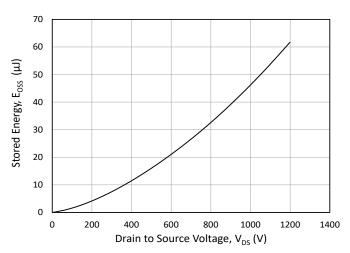


Figure 16. Output Capacitor Stored Energy

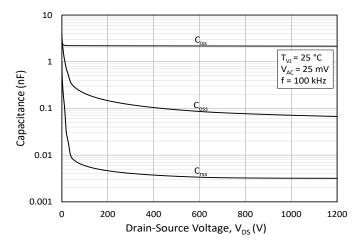


Figure 18. Capacitances vs. Drain-Source Voltage (0 - 1200 V)

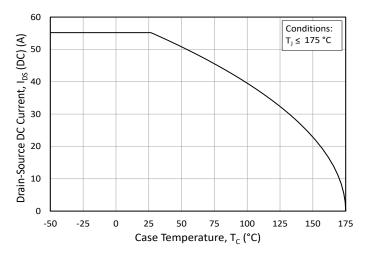


Figure 19. Continuous Drain Current Derating vs.

Case Temperature

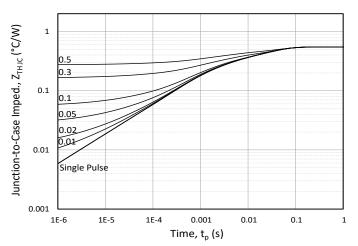


Figure 21. Transient Thermal Impedance (Junction - Case)

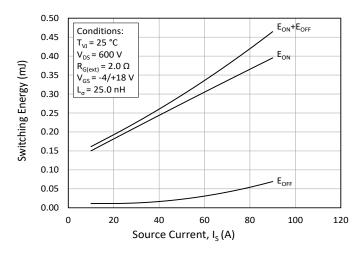


Figure 23. Clamped Inductive Switching Energy vs. Drain Current ($V_{DD} = 600 \text{ V}$)

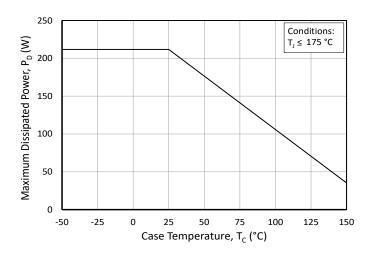


Figure 20. Maximum Power Dissipation Derating vs.

Case Temperature

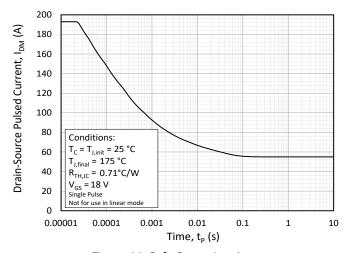


Figure 22. Safe Operating Area

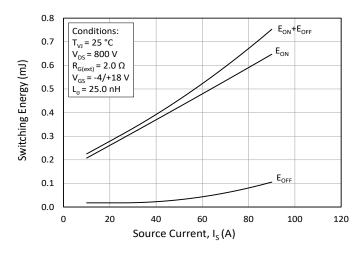


Figure 24. Clamped Inductive Switching Energy vs. Drain Current ($V_{DD} = 800 \text{ V}$)

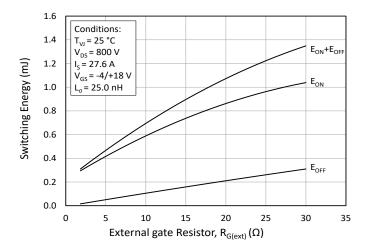


Figure 25. Clamped Inductive Switching Energy vs. $R_{G(ext)}$

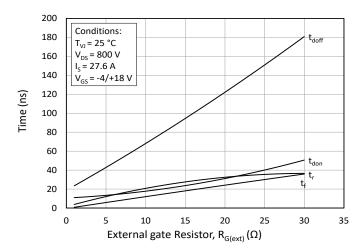


Figure 27. Switching Times vs. $R_{G(ext)}$

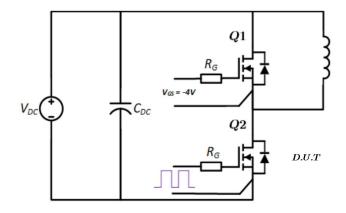


Figure 29. Clamped Inductive MOSFET Switching Waveform Test Circuit

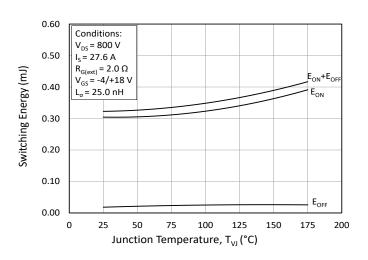


Figure 26. Clamped Inductive Switching Energy vs.
Temperature

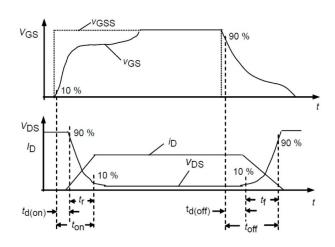


Figure 28. Switching Times Definition

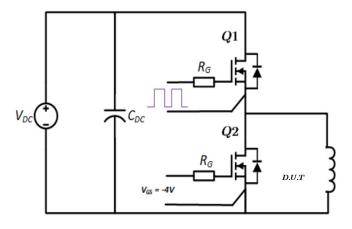
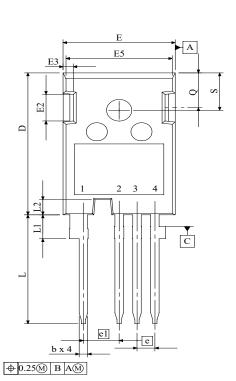
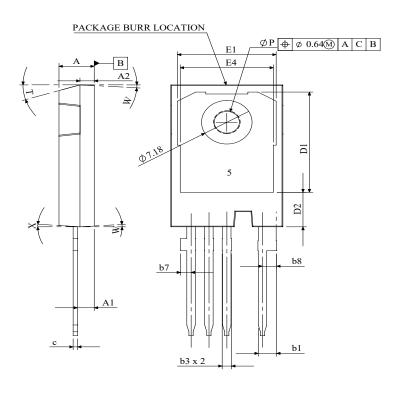


Figure 30. Clamped Inductive Body diode Switching Waveform Test Circuit

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Package Dimensions





SYMBOL	MIN (mm)	MAX (mm)				
A	4.83	5.21				
A1	2.23	2.54				
A2	1.91	2.16				
b	1.07	1.33				
b1	2.39	2.94				
b3	1.07	1.60				
b7	1.30	1.70				
b8	1.80	2.20				
c	0.55	0.68				
D	23.30	23.63				
D1	16.25	17.65				
D2	5.55	5.95				
E	15.75	16.13				
E1	13.1	14.15				
E2	3.68	5.10				
E3	1.00	1.90				
E4	12.38	13.43				
E5	14.65	15.05				
e1		BSC				
L	17.31	17.82				
L1	3.97	4.37				
L2	2.35	2.65				
ØΡ	3.51	3.65				
Q	5.49	6.00				
S	6.04	6.30				
T	17.5 ° REF.					
W	3.5 ° REF.					
X	4° REF.					

1	DRAIN			
2	SOURCE			
3	DRIVER SOURCE			
4	GATE			
5	DRAIN			

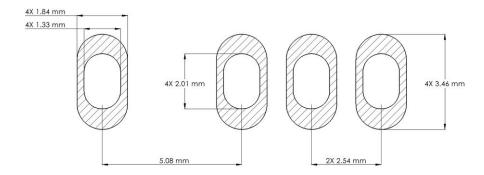
NOTE

- 1. ALL METAL SURFACES ARE TIN PLATED (MATTE), EXCEPT AREA OF CUT.
- 2. DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M-1994.
- 3. ALL DIMENSIONS ARE LISTED IN MILLIMETERS. ANGLES ARE IN DEGREES.
- 4. BURR OR MOLD FLASH SIZE (0.5 mm) IS NOT INCLUDED IN THE DIMENSIONS

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Recommended Solder Pad Lavout

All dimensions in mm



Revision history

Document Version	Date of release	Description of changes
1	November 2025	Initial release

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